

Product / Package Information

Package	LFCSF - Punched
Body Size (mm)	8 X 8 X 0.85 (5.0 EP)
Lead Count	56
Terminal Finish	100 Sn

Environmental Compliance Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Other inorganic materials	Silica	60676-86-0	7.17E-02	86.91	869100	33.66		336650
Thermosets	Epoxy & Phenol Resin	Proprietary	1.05E-02	12.78	127800	4.95		49504
Other inorganic materials	Carbon black	1333-86-4	2.56E-04	0.31	3100	0.12		1201
Subtotal			8.25 E-02	100.00	1000000	38.74		387355

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Copper & its alloys	Copper	7440-50-8	1.13 E-01	97.5	975000	52.96		529551
Copper & its alloys	Iron	7439-89-6	2.72 E-03	2.35	23500	1.28		12764
Copper & its alloys	Zinc	7440-66-6	1.39 E-04	0.12	1200	0.07		652
Copper & its alloys	Phosphorus	7723-14-0	3.47 E-05	0.03	300	0.02		163
Subtotal			1.16 E-01	100.00	1000000	54.31		543130

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious metals	Silver	7440-22-4	1.16 E-03	100.0	1000000	0.54		5431

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Tin & its alloys	Tin	7440-31-5	2.73 E-03	100.0	1000000	1.28		12823

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious metals	Gold	7440-57-5	1.54 E-03	100.0	1000000	0.72		7233

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Other inorganic materials	Doped Silicon	7440-21-3	8.19 E-03	100.0	1000000	3.85		38480

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious metals	Silver	7440-22-4	7.84 E-04	66.34	663400	0.37		3681
Thermoset	Epoxy resin	Proprietary	6.63 E-05	5.61	56100	0.03		311
Other organic materials	Aliphatic acid anhydride	Proprietary	6.63 E-05	5.61	56100	0.03		311
Other organic materials	2,6 diglycidyl phenyl allyl ether oligomer	Proprietary	6.63 E-05	5.61	56100	0.03		311
Other organic materials	Epoxy derivative	Proprietary	6.63 E-05	5.61	56100	0.03		311
Other organic materials	1,4-bis(2,3-epoxypropoxy)butane	Proprietary	6.63 E-05	5.61	56100	0.03		311
Other organic materials	Hexahydromethylphthalic anhydride	Proprietary	6.63 E-05	5.61	56100	0.03		311
Subtotal			1.18 E-03	100.0	1000000	0.55		5549

Package Totals			Weight (g)	2.13 E-01		Percentage (%)	100	PPM	1000000
-----------------------	--	--	-------------------	------------------	--	-----------------------	------------	------------	----------------

Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



ADI Proprietary